

Dual P-Channel 20V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)		
	0.018 at V _{GS} = - 4.5 V	- 8.9		
- 20	0.022 at V _{GS} = - 2.5 V	- 8.1		
	0.030 at V _{GS} = - 1.8 V	- 3.6		

8 D₁

 D_2

7 D₁

6 D₂

5

SO-8

 S_1

G1

S₂ 3

 G_2

2

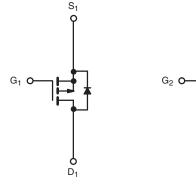
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- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- Advanced High Cell Density Process
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

Load Switching



P-Channel MOSFET

D₂ P-Channel MOSFET

S₂ 0

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \degree C$, unless otherwise noted						
Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 20		V	
Gate-Source Voltage		V _{GS}	± 12		v	
Continuous Drain Current $(T_J = 150 \ ^{\circ}C)^a$	T _A = 25 °C	– I _D	- 8.9	- 6.7	٨	
	T _A = 70 °C		- 7.1	- 5.4		
Pulsed Drain Current		I _{DM}	- 30		A	
Continuous Source Current (Diode Conduction) ^a		۱ _S	- 1.7	- 0.9		
	T _A = 25 °C	Pn	2.0	1.1	W	
Maximum Power Dissipation ^a	T _A = 70 °C	L L L L L L L L L L L L L L L L L L L	1.3	0.7	vv	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55	to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	t ≤ 10 s	- R _{thJA}	46	62.5	°C/W
Maximum Junction-to-Ambient ^a	Steady State		80	110	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	24	32	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.



FREE Available

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -350 \ \mu A$	- 0.4		- 1.0	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA
	I _{DSS}	$V_{DS} = -20 V, V_{GS} = 0 V$			- 1	
Zero Gate Voltage Drain Current		V_{DS} = - 20 V, V_{GS} = 0 V, T_{J} = 55 °C			- 5	μA
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 4.5 V	- 30			А
		V _{GS} = - 4.5 V, I _D = - 8.9 A		0.018		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 8.1 A		0.022	0.022	
		V _{GS} = - 1.8 V, I _D = - 3.6 A		0.030		1
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 8.9 A		26		S
Diode Forward Voltage ^a	V _{SD}	I _S = - 1.7 A, V _{GS} = 0 V		- 0.7	- 1.2	V
Dynamic ^b	•	·				
Total Gate Charge	Qg			34.5	52	
Gate-Source Charge	Q _{gs}	V_{DS} = - 10 V, V_{GS} = - 4.5 V, I_D = - 8.9 A		5.1		nC
Gate-Drain Charge	Q _{gd}			9.6		
Gate Resistance	Rg			9		Ω
Turn-On Delay Time	t _{d(on)}			25	40	
Rise Time	t _r	V_{DD} = - 10 V, R_L = 6 Ω		46	70	
Turn-Off Delay Time	t _{d(off)}	$I_{D}\cong$ - 1 A, V_{GEN} = - 4.5 V, R_{g} = 6 Ω		230	345	ns
Fall Time	t _f			155	235	
Source-Drain Reverse Recovery Time	-Drain Reverse Recovery Time t _{rr} I _F = - 1.7 A, dl/dt = 100 A/µs			128	200	

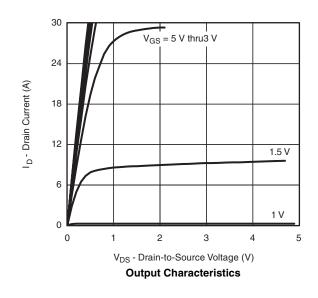
Notes:

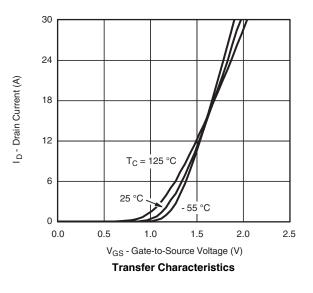
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

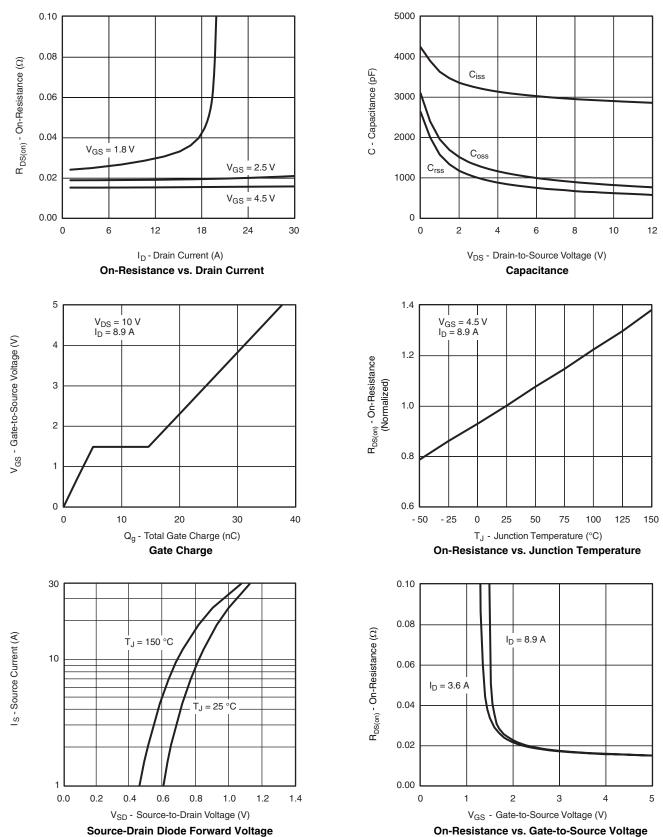




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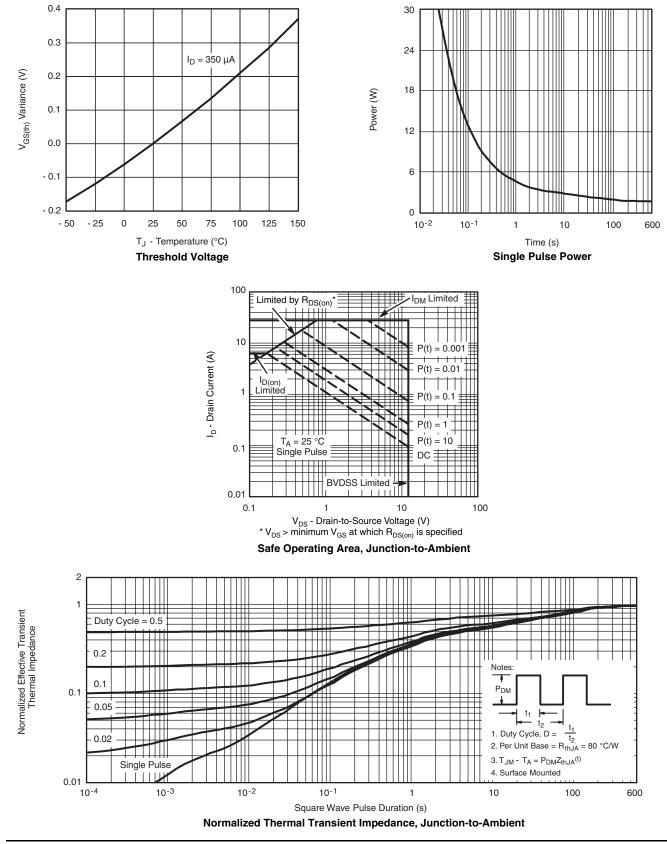
TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



服务热线:400-655-8788

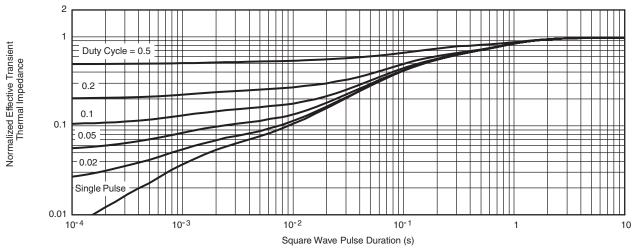








TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

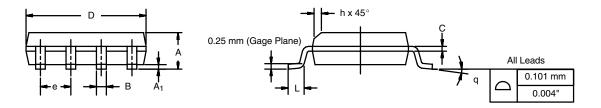


Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

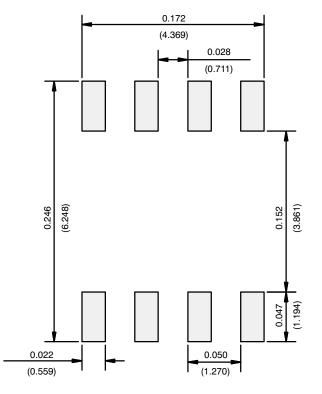




	MILLIM	IETERS	INCHES			
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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